

Advanced Semiconductor Engineering, Inc.



Conexant Recognizes ASE with 2003 Supplier of the Year Award

Santa Clara, California, February 25, 2004 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world's largest semiconductor packaging and testing companies, announced today that it has received a 2003 Supplier of the Year Award from Conexant (Nasdaq: CNXT). ASE was selected from among many key suppliers in recognition of having demonstrated outstanding leadership in assembly and test. This award reflects ASE's commitment to driving the future of emerging semiconductor technologies through its expertise in leading-edge packaging, substrate and test capabilities.

"We are very pleased to present this award to ASE, who has earned this recognition through their excellent customer service and support," said Karla Carichner, vice president of Operations for Conexant. "As a fabless semiconductor company, Conexant relies on the leadership capabilities of our suppliers to ensure the integrity of the assembly and test processes. In this capacity, ASE has clearly demonstrated their dedication to providing the highest caliber of services to Conexant."

"ASE is honored to be recognized by a valued customer such as Conexant," said Dr Tien Wu, President of ASE Americas, Europe and Japan. "This accolade underscores ASE's continued efforts to develop strategic long-term partnerships designed to support worldwide manufacturing service channels, while addressing ASE's customer satisfaction initiative. We look forward to continuing our strategic relationship with Conexant, and successfully blending our superior core technologies with a flexible, responsive organization focused on supporting our customers' business objectives and quality requirements."

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry's ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal

Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$2.9 billion in 2003 and employs over 29,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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